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Mobile DRAM

K4F6E304HB-MGCH

16Gb B-die Low Power DDR4 of 200FBGA

K4F6E304HB-MGCH

OVERVIEW

SPECIFICATIONS

Samsung LPDDR4 mobile DRAM is high-speed, power-saving memory built specifically for smartphones and tablets. LPDDR4 provides higher bandwidth and greater density for superb graphic resolution, smooth streaming multimedia and instant-on, instantplay performance. Multitasking, longer standby, larger screen sizes and thinner profiles are also possible using LPDDR4 mobile DRAM. When choosing Samsung LPDDR4 memory, manufacturers gain the following exceptional design advantages while end users benefit from enhanced performance.

SPECIFICATIONS

MOBILE DRAM > LOW POWER DDR4 > K4F6E304HB-MGCH

Density	16 Gb	Organization	x32
Speed	3200Mbps	Package	200FBGA
Vdd2 & Vddq	1.1V / 1.1V	Temperature	-25°C ~ 85°C
Production Status	Mass Production	Application	ULT, Tablet

DDR4

Temperature & Power

- C: Commercial Temp.(0°C~85°C) & Normal Power
- J: Industrial Temp.(-40°C~95°C) & Normal Power

Speed

- PB: DDR4-2133 (1066MHz @ CL=15, tRCD=15, tRP=15)
- RC: DDR4-2400 (1200MHz @ CL=17, tRCD=17, tRP=17)
- ID: DDR4-2666 (1333MHz @ CL=19, tRCD=19, tRP=19)

DDR3

Temperature & Power

- C: Commercial Temp.(0°C~85°C) & Normal Power(1.5V)

• Y: Commercial Temp.(0°C~85°C) & Low

Voltage(1.35V)

• M: Industrial Temp.(-40°C~95°C) & Low

Voltage(1.35V)

Speed

- EZ: DDR3-800 (400MHz @ CL=6, tRCD=6, tRP=6)
- F8: DDR3-1066 (533MHz @ CL=7, tRCD=7, tRP=7)
- H9: DDR3-1333 (667MHz @ CL=9, tRCD=9, tRP=9)
- K0: DDR3-1600 (800MHz @ CL=11, tRCD=11, tRP=11)

DDR2

Temperature & Power

- I: Industrial Temp.(-40°C~95°C) & Normal Power

Speed

- F8: DDR2-1066 (533MHz @ CL=7, tRCD=7, tRP=7)
- EZ: DDR2-800 (400MHz @ CL=5, tRCD=5, tRP=5)
- FZ: DDR2-800 (400MHz @ CL=6, tRCD=6, tRP=6)
- E6: DDR2-667 (667MHz @ CL=5, tRCD=5, tRP=5)

• **MA**: DDR3-1866 (933MHz @ CL=13, tRCD=13, tRP=13)
• **NB**: DDR3-2133 (1066MHz @ CL=14, tRCD=14, tRP=14)

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- PC DRAM
- Mobile DRAM
- Consumer DRAM
- Graphic DRAM
Flash Storage
- V-NAND Technology
- Client SSD
- Enterprise SSD
- eMMC
- UFS
MCP
- eMMC Based MCP
- ePoP

Exynos Solution
- Application Processor
- ModAP
- Modem/RF
ISOCELL Image Sensor
- Mobile CIS
- Industry CIS
Display Solution
- Mobile DDI
- Panel DDI/TCON
- Touch Controller
Security Solution
- Smart Card
- NFC
Power IC
Bio-Processor

APPLICATION

Data Center
- Web Server
- Application Server
- DB Server
- Storage Server
Mobile Device
- Smartphone
- Tablet
- Wearable
Consumer Device
- Desktop
- Notebook
- Smart TV
- Game Console
By Industry
- Automotive
- Industrial
- Banking/ID
- Healthcare & Wellness

FOUNDRY

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Manufacturing
Process Technology
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- 32/28nm
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- 65nm
Service
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